

PAD
 KEEP OUT AREA

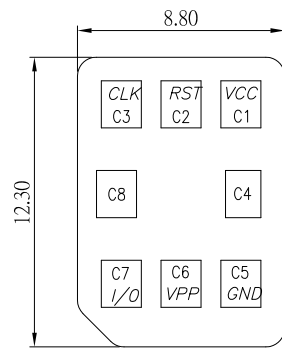
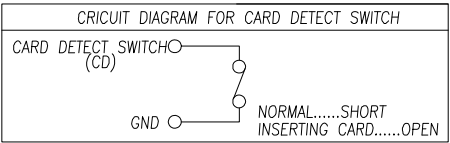
P.C.B LAYOUT MOUNTING PATTERN

MATERIALS:

- HOUSING : LCP
 - TERMINAL : PHOSPHOR BRONZE
 - SHELL : SUS
- Finish:
- Finish: CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
 - SHELL: NICKEL UNDER PLATED SURFACE LAYER

SPECIFICATION:

- RATING : 1.0A , 30V
- DIELECTRIC WITHSTANDING VOLTAGE : 500V AC
- INSULATION RESISTANCE : 1000MΩ MIN.
- CONTACT RESISTANCE : 50mΩ MAX.
- OPERATING TEMPERATURE : -40°C TO +85°C.



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

8	更新圖面	Jack	031921	10	更新樣式	Jack	030422
7	更新OPERATING TEMPERATURE	Jack	011521	9	更新材質	Jack	011122

6	更新圖面	Jack	121820
5	新增尺寸	Jack	120920
4	更新RATING	Jack	082420
3	更新圖面	Jack	052819
2	新增尺寸	Jack	052019
1	新增線路標示	Jack	051419
ITEM NO.	DESCRIPTION	DRAWN	DATE

建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :
 Up to 5 ±0.2
 Above 5 ~ 15 ±0.3
 Above 15 ~ 30 ±0.4
 Above 30 ~ 50 ±0.5
 Angle ±0.3

3RD. ANGEL'S

UNITS MM

DRAWN BY: Jack Lu
 CHECKED BY: Jacky Chen
 APPROVED BY: Tony Kao

DATE: 03/04/22
 DATE: 03/04/22
 DATE: 03/04/22

MAT'L		TITLE	CONNECTOR
FINISH		MODLE	Nano SIM CARD SOCKET 6PIN 1.35H
SCALE	1 : 1	DWG NO.	NSIM-510010632S-S304
SHEET NO.	1 of 1	PART NO.	NSIM-510010632S-S304
		SIZE	A4
		VER	R10